



Material Content Data Sheet



Sales Product Name				SAK-TC267D-40F200N BC		Issued		18. August 2019	
MA#				MA001672874					
Package				PG-LFBGA-292-6		Weight*		933.74 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	17.078	1.83	1.83	18290	18290	
wire	noble metal	palladium	7440-05-3	0.014	0.00		15		
	non noble metal	copper	7440-50-8	1.407	0.15	0.15	1507	1522	
encapsulation	organic material	carbon black	1333-86-4	0.718	0.08		769		
	plastics	epoxy resin	-	49.534	5.30		53048		
	inorganic material	silicondioxide	60676-86-0	308.688	33.09	38.47	330592	384409	
substrate	plastics	epoxy resin	-	6.479	0.69		6939		
	inorganic material	bariumsulfate	7727-43-7	9.942	1.06		10647		
	plastics	acrylic resin	-	11.506	1.23		12322		
	inorganic material	aluminiumhydroxide	21645-51-2	53.265	5.70		57045		
	plastics	epoxy bismaleimide triazine resin	-	61.156	6.55		65496		
	inorganic material	glass fibre	-	82.857	8.87		88736		
	non noble metal	copper	7440-50-8	196.577	21.05	45.15	210526	451711	
plating	noble metal	gold	7440-57-5	1.106	0.12		1184		
	non noble metal	nickel	7440-02-0	3.027	0.32	0.44	3242	4426	
solderball	noble metal	silver	7440-22-4	4.457	0.48		4774		
	non noble metal	tin	7440-31-5	122.898	13.16	13.64	131619	136393	
glue	plastics	epoxy resin	-	0.758	0.08		812		
	noble metal	silver	7440-22-4	2.275	0.24	0.32	2437	3249	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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